

HEF4543B

BCD to 7-segment latch/decoder/driver

Rev. 7 — 1 April 2016

Product data sheet

1. General description

The HEF4543B is a BCD to 7-segment latch/decoder/driver for liquid crystal and LED displays. It has four address inputs (D0 to D3), an active LOW latch enable input (\overline{LE}), an active HIGH blanking input (BL), an active HIGH phase input (PH) and seven buffered segment outputs (Qa to Qg).

The circuit provides the function of a 4-bit storage latch and an 8-4-2-1 BCD to 7-segment decoder/driver. It can invert the logic levels of the output combination. The phase (PH), blanking (BL) and latch enable (\overline{LE}) inputs are used to reverse the function table phase, blank the display and store a BCD code, respectively.

For liquid crystal displays, a square-wave is applied to PH and the electrical common back-plane of the display. The outputs of the device are directly connected to the segments of the liquid crystal.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

3. Ordering information

Table 1. Ordering information

All types operate from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

Type number	Package		Version
	Name	Description	
HEF4543BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



4. Functional diagram

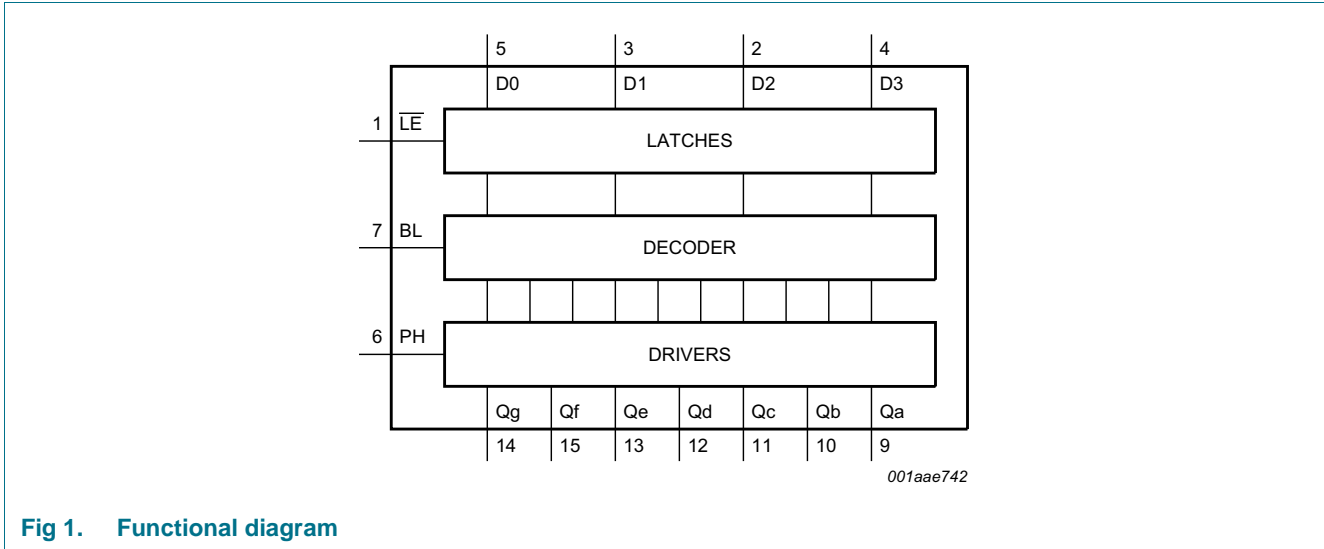


Fig 1. Functional diagram

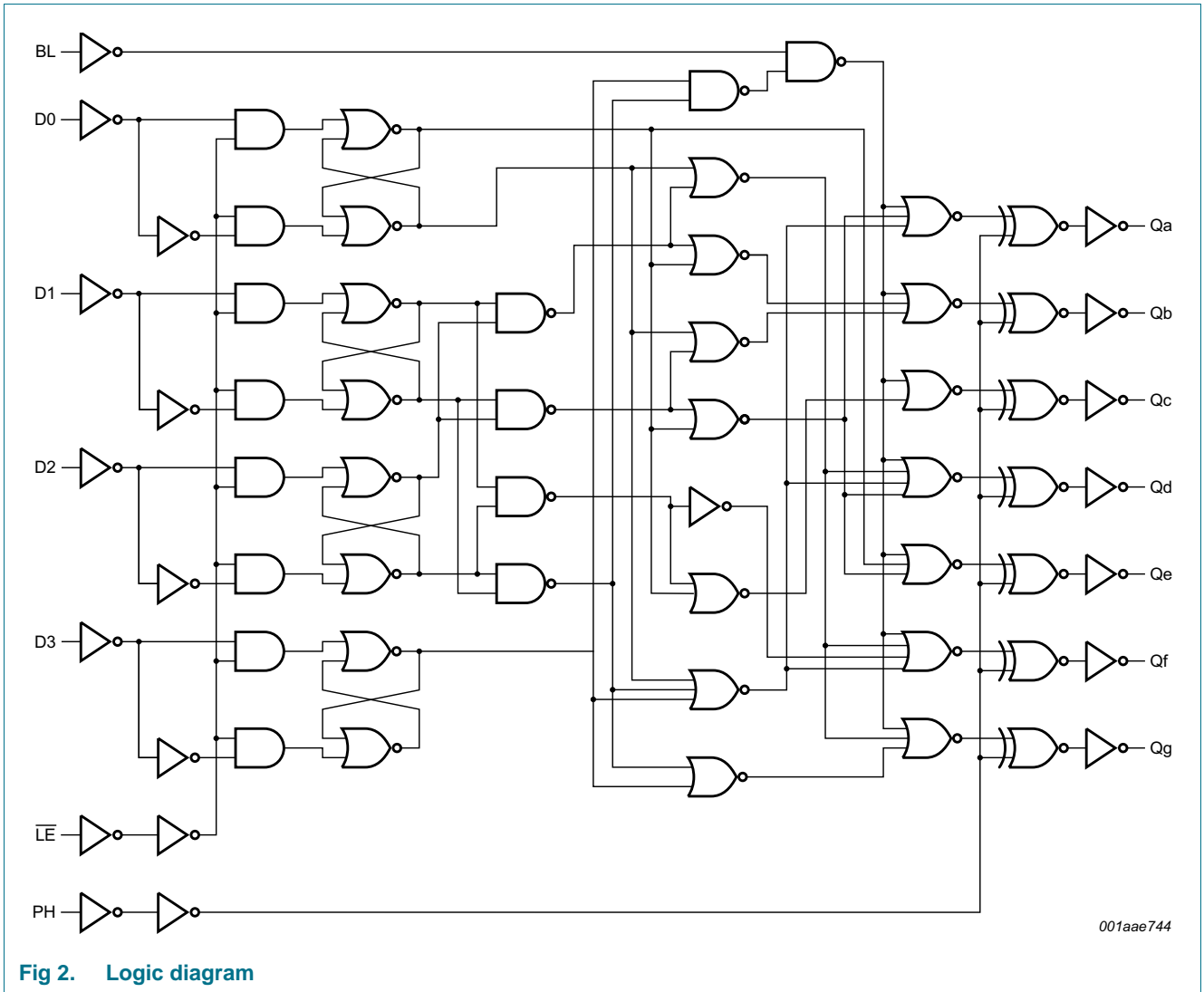
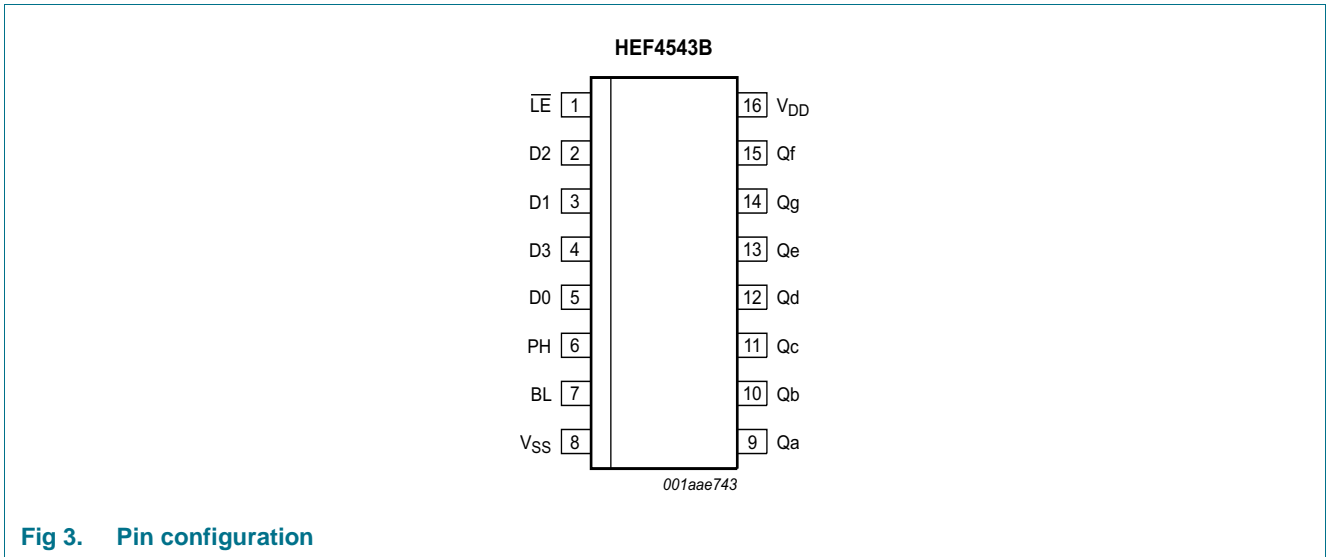


Fig 2. Logic diagram

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
\overline{LE}	1	latch enable input (active LOW)
D0 to D3	5, 3, 2, 4	address (data) input
PH	6	phase input (active HIGH)
BL	7	blanking input (active HIGH)
V_{SS}	8	ground supply voltage
Qa to Qg	9, 10, 11, 12, 13, 15, 14	segment output
V_{DD}	16	supply voltage

6. Functional description

Table 3. Function table [1]

Inputs							Outputs							Display
LE	BL	PH [2]	D3	D2	D1	D0	Qa	Qb	Qc	Qd	Qe	Qf	Qg	
X	H	L	X	X	X	X	L	L	L	L	L	L	L	blank
H	L	L	L	L	L	L	H	H	H	H	H	H	L	0
H	L	L	L	L	L	H	L	H	H	L	L	L	L	1
H	L	L	L	L	H	L	H	H	L	H	H	L	H	2
H	L	L	L	L	H	H	H	H	H	H	L	L	H	3
H	L	L	L	H	L	L	L	H	H	L	L	H	H	4
H	L	L	L	H	L	H	H	L	H	H	L	H	H	5
H	L	L	L	H	H	L	H	L	H	H	H	H	H	6
H	L	L	L	H	H	H	H	H	H	L	L	L	L	7
H	L	L	H	L	L	L	H	H	H	H	H	H	H	8
H	L	L	H	L	L	H	H	H	H	H	L	H	H	9
H	L	L	H	L	H	X	L	L	L	L	L	L	L	blank
H	L	L	H	H	X	X	L	L	L	L	L	L	L	blank
L	L	L	X	X	X	X	n.c.							n.c.
as above		H	as above				inverse of above							as above

- [1] H = HIGH voltage level; L = LOW voltage level; X = don't care; n.c. = no change.
- [2] For liquid crystal displays, apply a square-wave to PH;
For common cathode LED displays, select PH = LOW;
For common anode LED displays, select PH = HIGH.

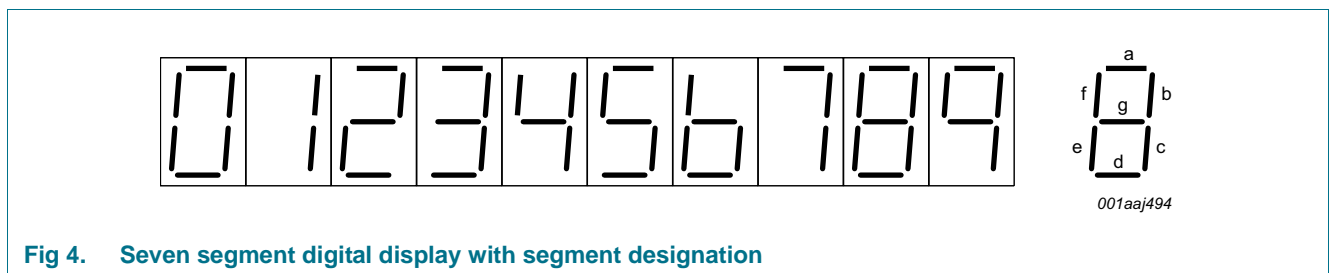


Fig 4. Seven segment digital display with segment designation

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DD}	supply voltage		-0.5	+18	V
V _I	input voltage		-0.5	V _{DD} + 0.5	V
I _{I/O}	input/output current		-	±10	mA
T _{stg}	storage temperature		-65	+150	°C

Table 4. Limiting values ...continued
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
T _{amb}	ambient temperature		-40	+85	°C
P _{tot}	total power dissipation	SO16 package [1]	-	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{DD}	supply voltage		3	-	15	V
V _I	input voltage		0	-	V _{DD}	V
T _{amb}	ambient temperature	in free air	-40	-	+85	°C
Δt/ΔV	input transition rise and fall rate	V _{DD} = 5 V	-	-	3.75	μs/V
		V _{DD} = 10 V	-	-	0.5	μs/V
		V _{DD} = 15 V	-	-	0.08	μs/V

9. Static characteristics

Table 6. Static characteristics
V_{SS} = 0 V; V_I = V_{SS} or V_{DD} unless otherwise specified.

Symbol	Parameter	Conditions	V _{DD}	T _{amb} = -40 °C		T _{amb} = 25 °C		T _{amb} = 85 °C		Unit
				Min	Max	Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	I _O < 1 μA	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
V _{IL}	LOW-level input voltage	I _O < 1 μA	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
V _{OH}	HIGH-level output voltage		5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V _{OL}	LOW-level output voltage	I _O < 1 μA	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I _{OH}	HIGH-level output current	V _O = 2.5 V	5 V	-	-1.7	-	-1.4	-	-1.1	mA
		V _O = 4.6 V	5 V	-	-0.52	-	-0.44	-	-0.36	mA
		V _O = 9.5 V	10 V	-	-1.3	-	-1.1	-	-0.9	mA
		V _O = 13.5 V	15 V	-	-3.6	-	-3.0	-	-2.4	mA

Table 6. Static characteristics ...continued
 $V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = 25\text{ }^{\circ}\text{C}$		$T_{amb} = 85\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	
I_{OL}	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.52	-	0.44	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.3	-	1.1	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	3.6	-	3.0	-	2.4	-	mA
I_I	input leakage current		15 V	-	± 0.3	-	± 0.3	-	± 1.0	μA
I_{DD}	supply current	$I_O = 0\text{ A}$	5 V	-	20	-	20	-	150	μA
			10 V	-	40	-	40	-	300	μA
			15 V	-	80	-	80	-	600	μA
C_I	input capacitance		-	-	-	-	7.5	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics
 $V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$; For test circuit see [Figure 7](#); unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula ^[1]	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	Dn to Qn; see Figure 5	5 V	$153\text{ ns} + (0.55\text{ ns/pF})C_L$	-	180	360	ns
			10 V	$64\text{ ns} + (0.23\text{ ns/pF})C_L$	-	75	150	ns
			15 V	$47\text{ ns} + (0.16\text{ ns/pF})C_L$	-	55	110	ns
		$\overline{\text{LE}}$ to Qn; see Figure 5	5 V	$143\text{ ns} + (0.55\text{ ns/pF})C_L$	-	170	340	ns
			10 V	$69\text{ ns} + (0.23\text{ ns/pF})C_L$	-	80	160	ns
			15 V	$52\text{ ns} + (0.16\text{ ns/pF})C_L$	-	60	120	ns
		BL to Qn; see Figure 5	5 V	$118\text{ ns} + (0.55\text{ ns/pF})C_L$	-	145	290	ns
			10 V	$54\text{ ns} + (0.23\text{ ns/pF})C_L$	-	65	130	ns
			15 V	$37\text{ ns} + (0.16\text{ ns/pF})C_L$	-	45	90	ns
t_{PLH}	LOW to HIGH propagation delay	Dn to Qn; see Figure 5	5 V	$153\text{ ns} + (0.55\text{ ns/pF})C_L$	-	180	360	ns
			10 V	$64\text{ ns} + (0.23\text{ ns/pF})C_L$	-	75	150	ns
			15 V	$47\text{ ns} + (0.16\text{ ns/pF})C_L$	-	55	110	ns
		$\overline{\text{LE}}$ to Qn; see Figure 5	5 V	$163\text{ ns} + (0.55\text{ ns/pF})C_L$	-	190	380	ns
			10 V	$69\text{ ns} + (0.23\text{ ns/pF})C_L$	-	80	160	ns
			15 V	$52\text{ ns} + (0.16\text{ ns/pF})C_L$	-	60	120	ns
		BL to Qn; see Figure 5	5 V	$98\text{ ns} + (0.55\text{ ns/pF})C_L$	-	125	250	ns
			10 V	$54\text{ ns} + (0.23\text{ ns/pF})C_L$	-	55	110	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
t_t	transition time	pin Qn; see Figure 5	5 V	$10\text{ ns} + (1.00\text{ ns/pF})C_L$	-	60	120	ns
			10 V	$9\text{ ns} + (0.42\text{ ns/pF})C_L$	-	30	60	ns
			15 V	$6\text{ ns} + (0.28\text{ ns/pF})C_L$	-	20	40	ns
t_{su}	set-up time	Dn to $\overline{\text{LE}}$; see Figure 6	5 V		40	20	-	ns
			10 V		20	5	-	ns
			15 V		15	0	-	ns

Table 7. Dynamic characteristics ...continued
 $V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ °C}$; For test circuit see [Figure 7](#); unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula ^[1]	Min	Typ	Max	Unit
t_h	hold time	Dn to \overline{LE} ; see Figure 6	5 V		0	-15	-	ns
			10 V		15	0	-	ns
			15 V		20	5	-	ns
t_w	pulse width	pin \overline{LE} HIGH; minimum width; see Figure 6	5 V		60	30	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns

[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C_L in pF).

Table 8. Dynamic power dissipation P_D
 P_D can be calculated from the formulas shown. $V_{SS} = 0\text{ V}$; $t_r = t_f \leq 20\text{ ns}$; $T_{amb} = 25\text{ °C}$.

Symbol	Parameter	V_{DD}	Typical formula for P_D (μW)	where:
P_D	dynamic power dissipation	5 V	$P_D = 2200 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_i = input frequency in MHz, f_o = output frequency in MHz, C_L = output load capacitance in pF, V_{DD} = supply voltage in V, $\Sigma(C_L \times f_o)$ = sum of the outputs.
		10 V	$P_D = 10400 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	
		15 V	$P_D = 33000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	

11. Waveforms

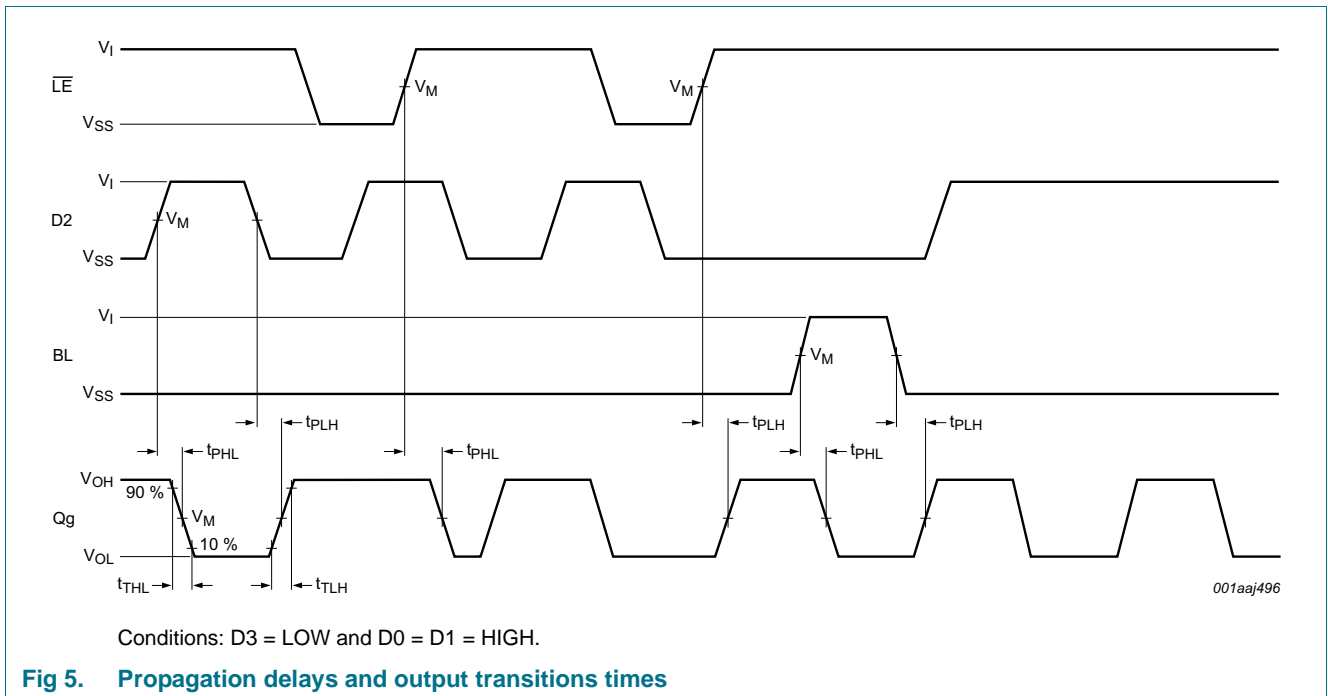
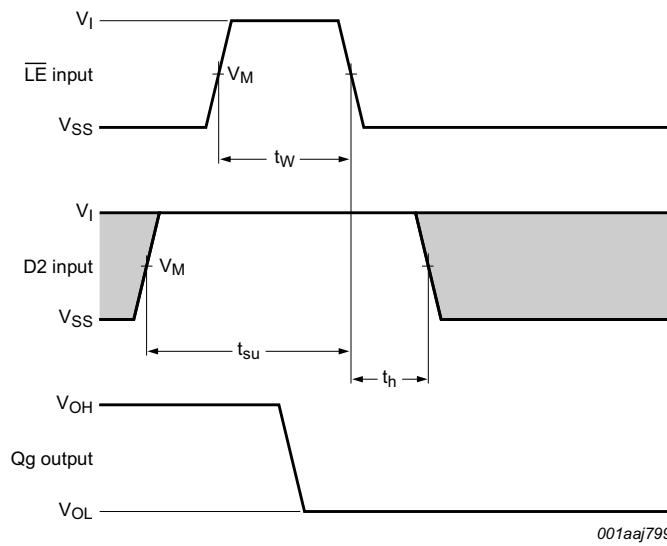


Fig 5. Propagation delays and output transitions times

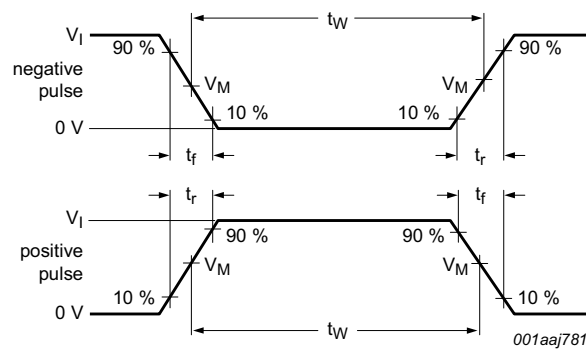


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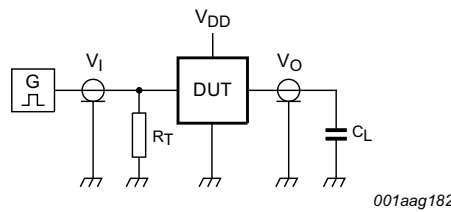
Conditions:

D3 = BL = LOW; D0 = D1 = \overline{LE} = HIGH

Fig 6. Waveforms showing minimum \overline{LE} pulse width, set-up, and hold time for DC to \overline{LE}



a. Input waveforms



b. Test circuit

Test data is given in [Table 9](#).

Definitions for test circuit:

R_L = Load resistance;

C_L = Load capacitance including jig and probe capacitance;

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 7. Test circuit for measuring switching times

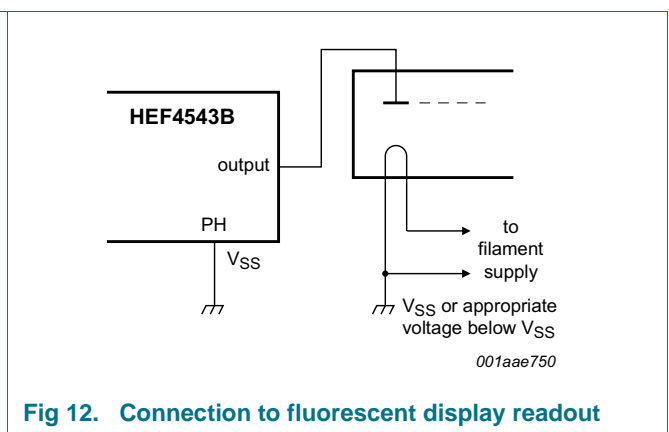
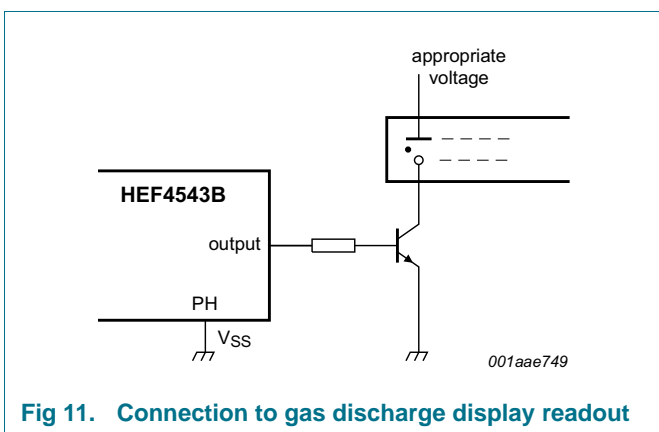
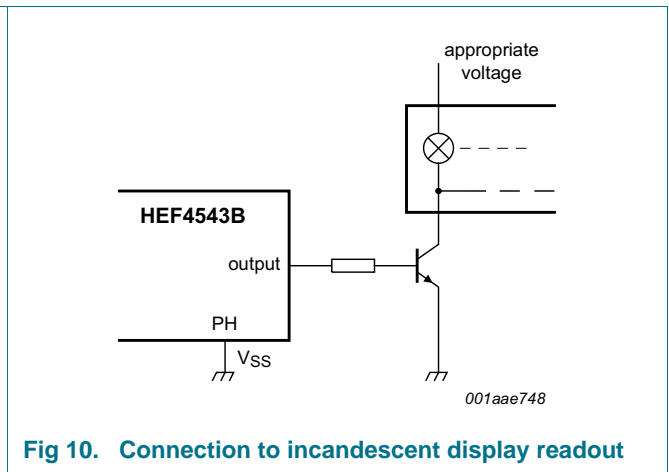
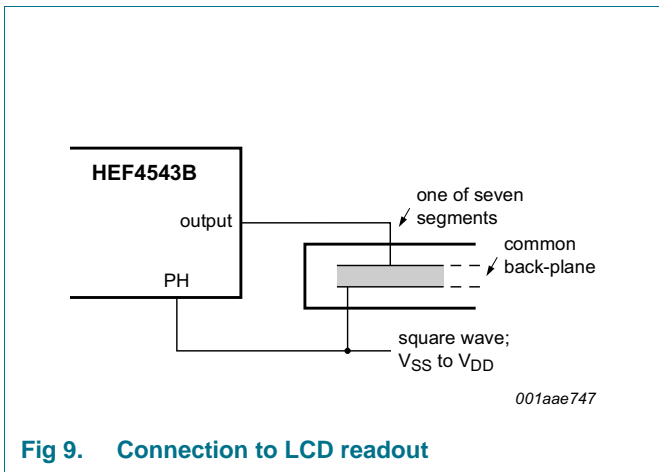
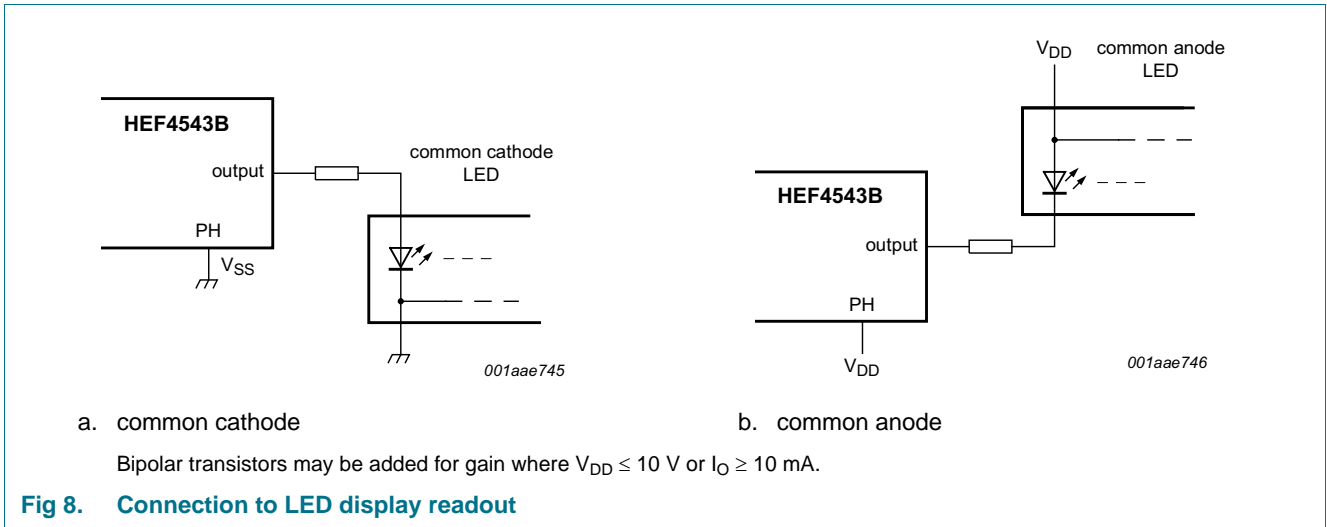
Table 9. Test data

Supply voltage	Input			Load
V_{DD}	V_I	V_M	t_r, t_f	C_L
5 V to 15 V	V_{DD}	$0.5V_I$	≤ 20 ns	50 pF

12. Application information

Some examples of applications for the HEF4543B are:

- Driving LCD displays
- Driving LED displays
- Driving fluorescent displays
- Driving incandescent displays
- Driving gas discharge displays



13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



Fig 13. Package outline SOT109-1 (SO16)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4543B v.7	20160401	Product data sheet	-	HEF4543B v.6
Modifications:	<ul style="list-style-type: none"> Type number HEF4543BP (SOT38-4) removed. 			
HEF4543B v.6	20111117	Product data sheet	-	HEF4543B v.5
Modifications:	<ul style="list-style-type: none"> Section Applications removed Table 6: I_{OH} minimum values changed to maximum Figure 6: signal \overline{LT} removed; signal \overline{BL} replaced by BL (inverted) 			
HEF4543B v.5	20091027	Product data sheet	-	HEF4543B v.4
HEF4543B v.4	20090317	Product data sheet	-	HEF4543B_CNV v.3
HEF4543B_CNV v.3	19950101	Product specification	-	HEF4543B_CNV v.2
HEF4543B_CNV v.2	19950101	Product specification	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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